



Integration Of Semiconductor Membranes With Piezoelectric Substrates

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The Invention

Piezoelectrically actuated devices constructed from thin semiconductor membranes bonded directly to piezoelectric substrates are provided. Methods for fabricating these devices are also provided. The bonding of the semiconductor to the piezoelectric material does not require the use of any intermediate layers, such as bonding agents.

Additional Information

For More Information About the Inventors

- [Max Lagally](#)

Publications

- [Scott et al. 2024. A Nanomechanical Transducer for Remote Signal Transmission onto the Tympanic Membrane–Playing Music on a Different Drum. Adv. Mater. Technol.](#)

Tech Fields

- [Semiconductors & Integrated Circuits : Design & fabrication](#)

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